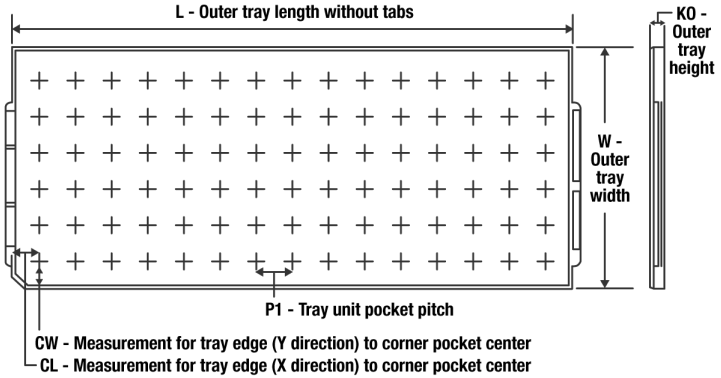
Carrier Material Report for LM185H-2.5-SMD

Tray Information:



Device	Package Drawing	Package Type	Pins	SPQ	Unit Array Matrix	Max Temp (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
LM185H-2.5-SMD	NDU	TO-CAN	2	20	2 X 10	150	126.49	61.98	10922	11.43	11.81	19.2

Images above are just a representation of the carrier. Actual carrier may vary. Please reference the dimensions provided in the table.

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